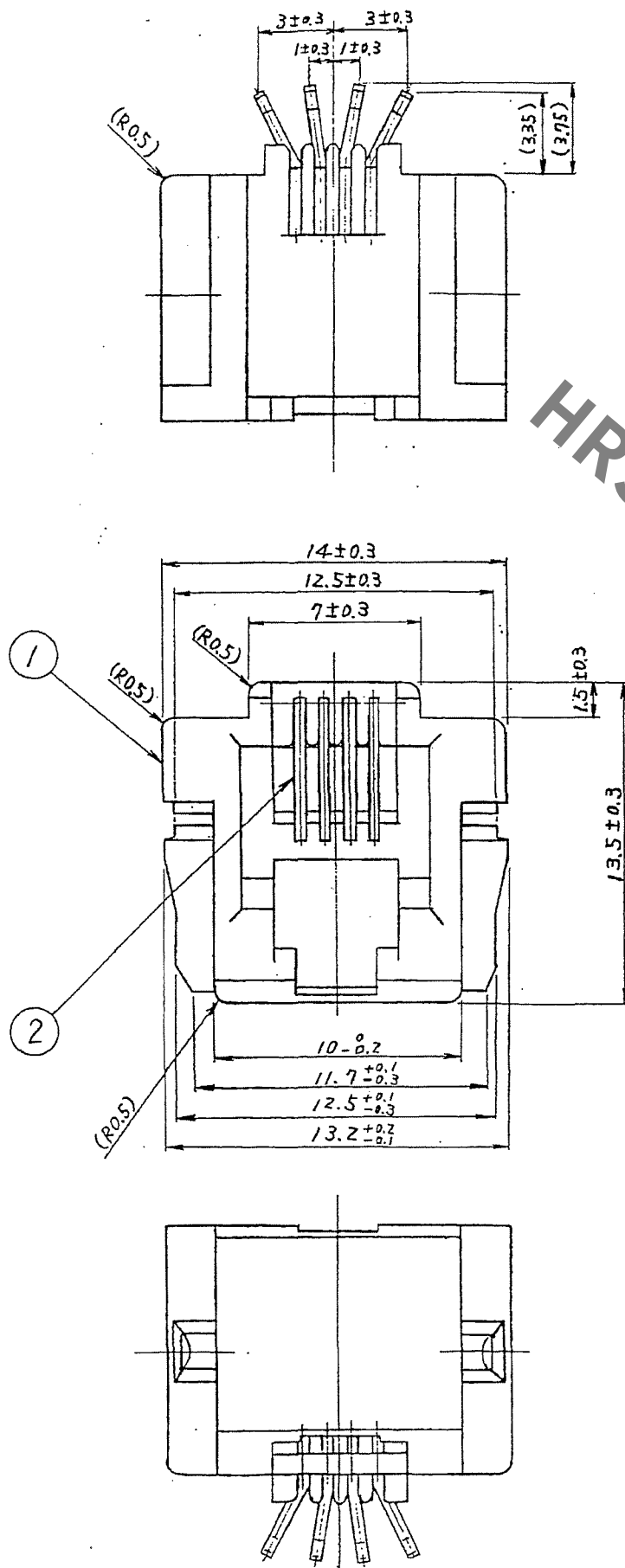
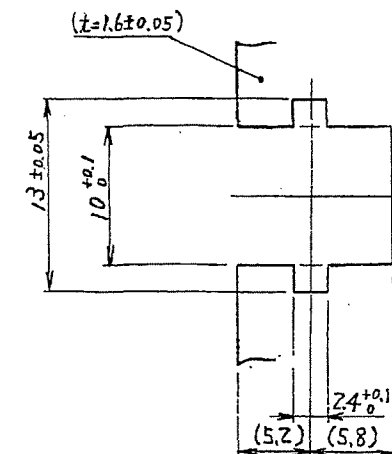
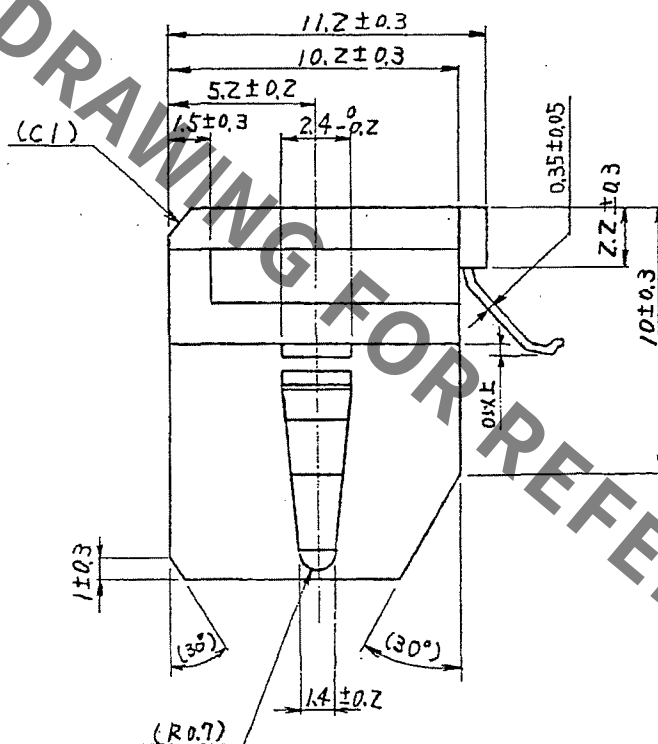
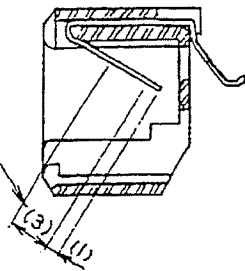


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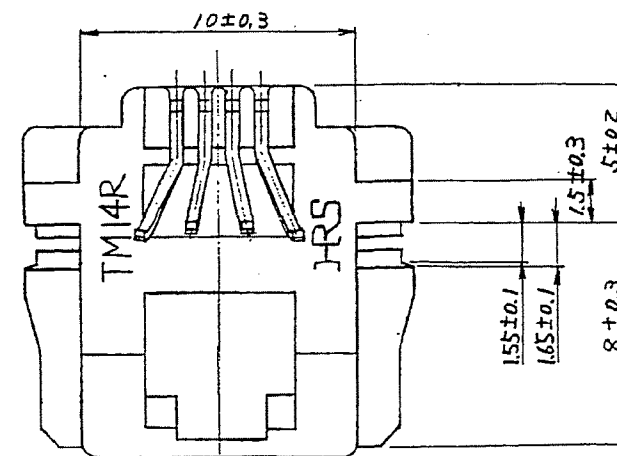
	COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	BY	CHKD	DATE
△					. .	△					. .
△					. .	△					. .
△					. .	△					. .



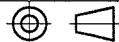
GOLD PLATING



RECOMMENDED PC BOARD PATTERN (2:1)



- NOTE 1. ABS RESIN IS APPLIED TO THE HOUSING, AND IT'S THERMAL DEFORMATION TEMPERATURE IS APPROX 80°C.
CONTACTS SHALL BE SOLDERED LOCALLY IN ROOM TEMPERATURE AND DO NOT USE SOLDERING METHODS WHICH APPLY HIGH TEMPERATURE TO THE COMPONENT.
2. FOR THE CONNECTOR MOUNTING, BE SURE TO FIX THE BODY TO THE DEVICE SUCH AS ADHESION NOT TO BE LOOSE BY EXTERNAL FORCE.
 3. THE DIMENSIONS IN PARENTHESIS ARE FOR REFERENCE.

			2	PHOSPHOR BRONZE	CONTACT: GOLD PLATING 0.5um min LEAF: GOLD PLATING 0.03um min UNDER: NICKEL PLATING 1.27um min		
1	PBT	(BLACK)UL94V-0					
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS		
CODE NO. (OLD)			DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED
			M. Itano 07.02.22	M. Itano 07.02.22	Y. Enami 07.02.22	J. Minami 07.02.23	.
		DRAWING NO.		PART NO.			
SCALE 2 : 1		EDC3-029831-01		TM14R-E44(50)			
UNITS mm		 HIROSE ELECTRIC CO., LTD		CODE NO.		CL222-1953-7-50	
						1/1	